

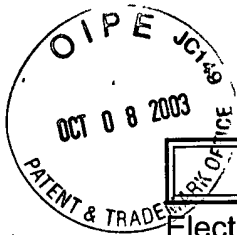


Electronic Filing System (EFS) Data
Electronic Patent Application Submission
USPTO Use Only


EFS ID: 49077
Application ID: 10610016 
Title of Invention: MAKING THERMALLY ENHANCED
CHIP SCALE LEAD CHIP
SEMICONDUCTOR PACKAGES
First Named Inventor: David McCann
Domestic/Foreign Application: Domestic Application
Filing Date: 2003-10-03
Effective Receipt Date: 2003-10-09
Submission Type: Information Disclosure
Statement
Filing Type:
Confirmation number: 1207
Attorney Docket Number: AMKOR038C

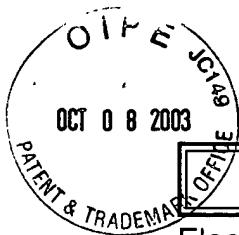
Total Fees Authorized:

Digital Certificate Holder: cn=Mark B. Garred,ou=Registered Attorneys,ou=Patent and Trademark
Office,ou=Department of Commerce,o=U.S. Government,c=US
Certificate Message Digest: a2c7a5ca0e57c711d391e3dbe92799b2acc143a2

**TRANSMITTAL**

Electronic Version v1.1
Stylesheet Version v1.1.0

Title of Invention	MAKING THERMALLY ENHANCED CHIP SCALE LEAD CHIP SEMICONDUCTOR PACKAGES									
<p>Application Number: 10/610016 </p> <p>Date: 2003-10-03</p> <p>First Named Applicant: David R. McCann</p> <p>Confirmation Number: 1207</p> <p>Attorney Docket Number: AMKOR038C</p>										
<p>I hereby certify that the use of this system is for OFFICIAL correspondence between patent applicants or their representatives and the USPTO. Fraudulent or other use besides the filing of official correspondence by authorized parties is strictly prohibited, and subject to a fine and/or imprisonment under applicable law.</p> <p>I, the undersigned, certify that I have viewed a display of document(s) being electronically submitted to the United States Patent and Trademark Office, using either the USPTO provided style sheet or software, and that this is the document(s) I intend for initiation or further prosecution of a patent application noted in the submission. This document(s) will become part of the official electronic record at the USPTO.</p>										
<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>Mark B. Garred Registered Number: 34,823</td><td>/mbg/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	Mark B. Garred Registered Number: 34,823	/mbg/	Attorney		
Submitted by:	Elec. Sign.	Sign. Capacity								
Mark B. Garred Registered Number: 34,823	/mbg/	Attorney								
<table><tr><td>Documents being submitted</td><td>Files</td></tr><tr><td>us-ids</td><td>ids3-usidst.xml</td></tr><tr><td></td><td>us-ids.dtd</td></tr><tr><td></td><td>us-ids.xsl</td></tr></table>			Documents being submitted	Files	us-ids	ids3-usidst.xml		us-ids.dtd		us-ids.xsl
Documents being submitted	Files									
us-ids	ids3-usidst.xml									
	us-ids.dtd									
	us-ids.xsl									
Comments										



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18
Stylesheet Version v18.0

Title of
Invention

MAKING THERMALLY ENHANCED CHIP SCALE LEAD
CHIP SEMICONDUCTOR PACKAGES

Application Number: 10/610016



Confirmation Number: 1207

First Named Applicant: David McCann

Attorney Docket Number: AMKOR038C

Art Unit: 2811

Search string: (5673479 or 5683806 or 5689135 or 5696666
or 5701034 or 5703407 or 5710064 or 5723899
or 5736432 or 5745984 or 5753977 or 5766972
or 5770888 or 5776798 or 5783861 or 5801440
or 5814877 or 5814881 or 5814883 or 5814884
or 5817540 or 5818105 or 5821457 or 5821615
or 5834830 or 5835988 or 5844306 or 5856911
or 5859471 or 5866939 or 5871782 or 5874784
or 5877043 or 5886397 or 5886398 or 5894108
or 5897339 or 5900676 or 5903049 or 5903050
or 5909053 or 5917242 or 5939779 or 5942794
or 5951305 or 5959356 or 5969426 or 5973388
or 5976912 or 5977613).pn.

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	5673479	1997-10-07	HAWTHORNE			
	2	5683806	1997-11-04	SAKUMOTO ET AL.			
	3	5689135	1997-11-18	BALL			
	4	5696666	1997-12-09	MILES ET AL.			
	5	5701034	1997-12-23	MARRS			
	6	5703407	1997-12-30	HORI			
	7	5710064	1998-01-20	SONG ET AL.			
	8	5723899	1998-03-03	SHIN			
	9	5736432	1998-04-07	MACKESSY			

10	5745984	1998-05-05	COLE, JR. ET AL.
11	5753977	1998-05-19	KUSAKA ET AL.
12	5766972	1998-06-16	TAKAHASHI ET AL.
13	5770888	1998-06-23	SONG ET AL.
14	5776798	1998-07-07	QUAN ET AL.
15	5783861	1998-07-21	SON
16	5801440	1998-09-01	CHU ET AL.
17	5814877	1998-09-29	DIFFENDERFER ET AL.
18	5814881	1998-09-29	ALAGARATNAM ET AL.
19	5814883	1998-09-29	SAWAI ET AL.
20	5814884	1998-09-29	DAVIS ET AL.
21	5817540	1998-10-06	WARK
22	5818105	1998-10-06	KOUDA
23	5821457	1998-10-13	MOSLEY ET AL.
24	5821615	1998-10-13	LEE
25	5834830	1998-11-10	CHO
26	5835988	1998-11-10	ISHII
27	5844306	1998-12-01	FUJITA ET AL.
28	5856911	1999-01-05	RILEY
29	5859471	1999-01-12	KURAISHI ET AL.
30	5866939	1999-02-02	SHIN ET AL.
31	5871782	1999-02-16	CHOI
32	5874784	1999-02-23	AOKI ET AL.
33	5877043	1999-03-02	ALCOE ET AL.
34	5886397	1999-03-23	EWER
35	5886398	1999-03-23	LOW ET AL.
36	5894108	1999-04-13	MOSTAFAZADEH ET AL.
37	5897339	1999-04-27	SONG ET AL.
38	5900676	1999-05-04	KWEON ET AL.
39	5903049	1999-05-11	MORI
40	5903050	1999-05-11	THURAIRAJARATNAM ET AL.
41	5909053	1999-06-01	FUKASE ET AL.
42	5917242	1999-06-29	BALL
43	5939779	1999-08-17	KIM
44	5942794	1999-08-24	OKUMURA ET AL.
45	5951305	1999-09-14	HABA

	46	5959356	1999-09-28	OH
	47	5969426	1999-10-19	BABA ET AL.
	48	5973388	1999-10-26	CHEW ET AL.
	49	5976912	1999-11-02	FUKUTOMI ET AL.
	50	5977613	1999-11-02	TAKATA ET AL

Signature

Examiner Name	Date